IN THE CLAIMS

Please amend the claims as follows:

Claims 1-28 (Canceled)

Claim 29 (New): A component to be mounted on a transfer surface, comprising:

at least one layer defining a plane in which at least one transfer face of the component, not parallel to the plane, comprises at least one metallized bonding land enabling assembly of the component by transfer and soldering of the metallized bonding lands onto the transfer surface,

wherein the at least one metallized bonding land of the component is arranged in a recessed notch set back from the surface of the transfer face.

Claim 30 (New): A component according to claim 29, further comprising at least one active layer.

Claim 31 (New): A component according to claim 30, wherein the at least one active layer is an optically active layer.

Claim 32 (New): A component according to claim 29, further comprising a support platform forming a transfer surface and including metallized mounting lands corresponding to the metallized bonding lands of the component.

Claim 33 (New): A component according to claim 29, wherein the at least one metallized bonding land is arranged at a border of the transfer face of the component.

Claim 34 (New): A component according to claim 29, wherein the transfer face comprises at least two metallized lands arranged along two opposite edges of the transfer face.

Claim 35 (New): A component according to claim 29, wherein the transfer face comprises four metallized lands arranged at corners of the transfer face.

Claim 36 (New): A component according to claim 29, wherein plural faces of the component forming the transfer faces comprise metallized bonding lands.

Claim 37 (New): A component according to claim 29, wherein the at least one metallized bonding land is arranged on each transfer face and represents a major part of the surface area of the transfer face.

Claim 38 (New): A component according to claim 29, wherein an intermediate element is placed between the transfer face of the component and the transfer surface.

Claim 39 (New): A component according to claim 38, wherein the intermediate element is placed between the component and the transfer surface with a shim or positioning adjustment stop function.

Claim 40 (New): A component according to claim 38, wherein the intermediate element is a heat sink or a cooler.

Claim 41 (New): A component according to claim 29, comprising plural layers of distinct media arranged parallel to the plane.

Claim 42 (New): A component according to claim 29, forming an optical resonant cell for coherent light, two opposite side faces parallel to the plane comprising reflecting layers.

Claim 43 (New): A method of assembly of a device in which at least one component including at least one layer defining a plane is transferred onto a transfer surface, the method comprising:

depositing a metallization on at least one transfer face of the component, not parallel to the plane, so as to form one or more metallized bonding lands; then,

transferring the component onto the transfer surface; and

making a solder, between each metallized bonding land of the transferred component and the transfer surface; and

prior to forming the metallized lands:

providing at least one notch excavated and set back from the transfer surface of the component in the transfer face of the component; and

depositing metallization in notches so as to form metallized lands set back from the transfer surface of the component.

Claim 44 (New): A method of assembly according to claim 43, further comprising:

providing a support platform comprising the transfer surface for the component; and

making a metallization deposit on the surface of the platform.

Claim 45 (New): A method of assembly according to claim 44, in which the depositing a metallization metallizes one or more mounting lands distributed around the surface of the platform, the location of the one or more metallized mounting lands corresponding to transfer locations of the metallized bonding lands of the component to be transferred.

Claim 46 (New): A method of assembly according to claim 44, in which the depositing a metallization metallizes one or more mounting lands on the surface of the platform, each metallized mounting land corresponding and surrounding a transfer position of plural metallized bonding lands of the component to be transferred.

Claim 47 (New): A method according to claim 43, further comprising:

excavating at least two assembly notches for each side face of the component to be transferred; and

forming at least two metallized mounting lands for each side face of a component to be transferred, so as to actively adjust an angular axial alignment of the component with respect to an axis with 2 degrees of freedom.

Claim 48 (New): A method according to claim 43, further comprising:

excavating four assembly notches for each face of the component to be transferred; then,

forming four metallized mounting lands at bottoms of four notches of each face of the component to be transferred, so as to actively adjust an angular axial alignment of the transferred component with respect to an axis with three degrees of freedom.

Claim 49 (New): A process for manufacturing components according to claim 29, comprising:

providing a substrate wafer comprising a blank of the component;

etching or cutting a series of parallel slits in the wafer, the slits being excavated from a portion of thickness of the substrate; and,

depositing a metallization at a bottom of the slits previously etched in the thickness of the wafer.

Claim 50 (New): A manufacturing process according to claim 49, in which the etching comprises:

depositing at least one layer of photoresist covering at least one face of the substrate wafer;

insolating the at least one layer of photoresist through an etching mask with a series of parallel opening slits; and

performing etching through the insolated photoresist, etching extending towards a core of the substrate and stopping on one portion of the thickness of the wafer, to prevent separating the wafer.

Claim 51 (New): A manufacturing process according to claim 49, in which the series of parallel slits includes slits that extend longitudinally so as to form trenches or grooves in the surface of the wafer.

Claim 52 (New): A manufacturing process according to claim 49, in which the series of parallel slits includes at least two parallel strips of short transverse slits so as to excavate a network of cavities in the surface of the wafer.

Claim 53 (New): A process according to claim 49, in which the depositing a metallization includes plural operations to deposit successive layers of distinct metals.

Claim 54 (New): A process according to the claim 53, in which the depositing a metallization includes three operations for successive deposition of titanium, nickel, and gold to obtain a Ti/Ni/Au triple layer.

Claim 55 (New): A process according to claim 49, in which the depositing a metallization is performed by cathodic sputtering by evaporation or by chemical vapour phase deposition.

Claim 56 (New): A process according to claim 49, further comprising:

finishing cutting by etching of the components by performing another etching operation or mechanical cutting directed along an extension of the axis of the slits, in which a cut line is narrower than a separation thickness of the slits.